

## Advanced Packaging and 3D Heterogeneous Integration for RF/mmWave Applications

Wednesday, September 27, 2023  
14:00-16:30  
online

### Agenda

14:00-14:05	Welcome	Yves Gigase, Chips JU
14:05-14:10	Introduction & short intro of Pack4EU and its goals	Martin Martens, VDI/VDE-IT
14:10-14:25	Portfolio analysis on the topic in ECSEL & KDT funding &	Eric Fribourg-Blanc, Chips JU
14:25-14:45	Overview on State of the art and future Challenges of RF/ mmWave packaging for various applications	Ivan Ndip, Fraunhofer IZM
14:45-15:00	SMART3 – An initiative fueling an European based platform for advanced packaging applied to heterogeneous mixed Analog / Digital SiP	Didier Floriot, UMS
15:00-15:15	Addressing the packaging needs towards enabling mmWave solutions	Rajesh Mandamparambil, NXP
15:15-15:30	Towards 6G components	Kristoffer Anderson, Ericsson
15:30-15:45	Introduction of potential Chips JU Focus Topic Call	Eric Fribourg-Blanc, Chips JU
15:45- 16:00	Discussion and Q&A on Call text	all
16:00- 16:20	Company and project idea pitches	CITC XTPL Finar Module S.a.g.l. 3DiS-Tech Ansys CSEM
16:20-16:30	Wrap-up of workshop	Moderator   Eric Fribourg-Blanc

### Chips JU Consultation Workshop on Advanced Packaging and 3D Heterogeneous Integration for RF/mmWave Applications

September 27, 2023 | 14:00-16:30 | online

Organised by Pack4EU and Chips JU

